

Title (en)

Electroless plating process and pretreating agent used therefor

Title (de)

Stromloses Plattierungsverfahren und Mittel zur Vorbehandlung von diesem

Title (fr)

Procédé de dépôt chimique et agent de prétraitement utilisé pour ceci

Publication

EP 1148153 A2 20011024 (EN)

Application

EP 00307877 A 20000912

Priority

JP 2000087406 A 20000327

Abstract (en)

An absolutely novel electroless plating process including a step of applying a pretreating solution containing a conductive metal oxide to a material to be treated before application of a catalyst thereto, which process gives less environmental impact, which is less expensive, and which can achieve more efficient and secured reductive deposition of a metal contained in a plating solution; and a pretreating agent used therefor. In the electroless plating process, a film containing a conductive metal oxide is formed on a surface of a nonconductive material, and the resulting nonconductive material is subjected to electroless plating. The pretreating agent contains at least a conductive metal oxide, a resin, and a substance which captures and immobilizes a reduction catalyst metal.

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C23C 18/18

IPC 8 full level

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CPC (source: EP KR)

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Cited by

CN104109537A; AU2013214694B2; EP1491656A1; EP2912211A4; CN115057630A; US10085351B2; US7825058B2; US7842636B2; US7510993B2

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